

N-Channel Enhancement Mode Power MOSFET

Description :

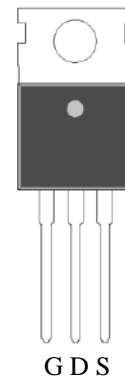
The KE3607 is a N-channel enhancement-mode MOSFET, providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The TO-220 package is universally preferred for all commercial-industrial applications

BV_{DSS} : 75V

R_{DSON} : 6 mΩ(typ.)

I_D : 80A

TO-220

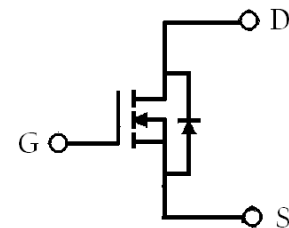


Features:

- Low On Resistance
- Simple Drive Requirement
- Low Gate Charge
- Fast Switching Characteristic
- RoHS compliant package

Applications :

- Switching Mode Power Supply
- Uninterruptible Power Supply
- High Speed Power Switching
- Hard Switched and High Frequency Circuits



G : Gate

D : Drain

S : Source

Ordering Information

Device	Package	Shipping
KE3607	TO-220 (RoHS compliant package)	50 pcs/tube, 20 tubes/box, 4 boxes / carton

Absolute Maximum Ratings (T_C=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage (Note 1)	V _{DS}	75	V
Gate-Source Voltage	V _{GS}	±20	
Continuous Drain Current @ V _{GS} =10V, T _C =25°C (silicon limit)	I _D	122*	A
Continuous Drain Current @ V _{GS} =10V, T _C =25°C (package limit)		80*	
Continuous Drain Current @ V _{GS} =10V, T _C =100°C (silicon limit)		86*	
Pulsed Drain Current @ V _{GS} =10V (Note 2)	I _{DM}	320*	
Single Pulse Avalanche Energy (Note 3)	E _{AS}	450	mJ
Single Pulse Avalanche Current @ L=0.1mH (Note 3)	I _{AS}	50	A
Repetitive Avalanche Energy (Note 2)	E _{AR}	23	mJ
ESD susceptibility (Note 4)	V _{ESD}	1500	V
Maximum Temperature for Soldering @ Lead at 0.125in(3.175mm) from case for 10 seconds	T _L	300	°C
Total Power Dissipation (T _C =25°C)	P _D	230	W
Linear Derating Factor above 25°C		1.53	W/°C
Operating Junction and Storage Temperature	T _j , T _{stg}	-55~+175	°C

*Calculated continuous drain current based on maximum allowable junction temperature.

- Note :
1. T_J=+25°C to +150°C.
 2. Repetitive rating; pulse width limited by maximum junction temperature.
 3. I_{AS}=30A, V_{DD}=25V, L=1mH, R_G=25Ω, starting T_J=+25°C.
 4. Human body model, 1.5kΩ in series with 100pF.

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{\theta JC}$	0.65	°C/W
Thermal Resistance, Junction-to-ambient, max	$R_{\theta JA}$	62	

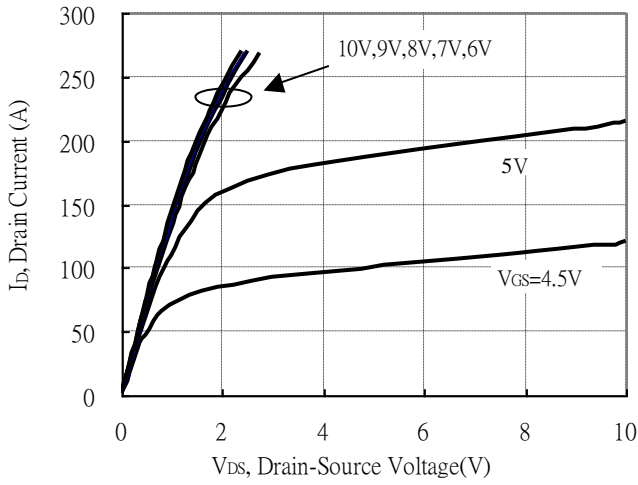
Characteristics (T_j=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	75	-	-	V	$V_{GS}=0V, I_D=250\mu A$
$V_{GS(th)}$	2.0	-	4.0		$V_{DS} = V_{GS}, I_D=250\mu A$
* G_{FS}	-	26.4	-	S	$V_{DS} = 10V, I_D=20A$
I_{GSS}	-	-	±100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
I_{DSS}	-	-	1	μA	$V_{DS} = 60V, V_{GS}=0V$
	-	-	10		$V_{DS} = 50V, V_{GS} = 0V, T_j=125^\circ C$
* $R_{DS(ON)}$	-	6	8	mΩ	$V_{GS} = 10V, I_D=37.5A$
Dynamic					
* Q_g	-	78.8	-	nC	$I_D=37.5A, V_{DD}=38V, V_{GS}=10V$
* Q_{gs}	-	15.7	-		
* Q_{gd}	-	22.4	-		
* $t_{d(ON)}$	-	30.2	-	ns	$V_{DD}=38V, I_D=75A, V_{GS}=10V, R_G=3.3\Omega$
* t_r	-	9.2	-		
* $t_{d(OFF)}$	-	67.8	-		
* t_f	-	13.8	-		
C_{iss}	-	3944	-	pF	$V_{GS}=0V, V_{DS}=25V, f=1MHz$
C_{oss}	-	365	-		
C_{rss}	-	208	-		
R_g	-	0.9	-	Ω	f=1MHz
Source-Drain Diode					
* I_S	-	-	80	A	
* I_{SM}	-	-	320		
* V_{SD}	-	0.85	1.5	V	$I_S=37.5A, V_{GS}=0V$
* t_{rr}	-	22.4	-	ns	$V_{GS}=0, I_F=75A, dI_F/dt=100A/\mu s$
* Q_{rr}	-	17.5	-	nC	

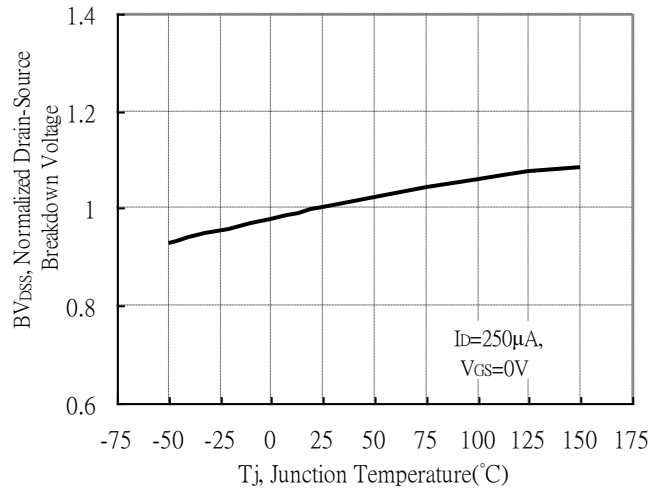
*Pulse Test : Pulse Width ≤300μs, Duty Cycle ≤2%

Typical Characteristics

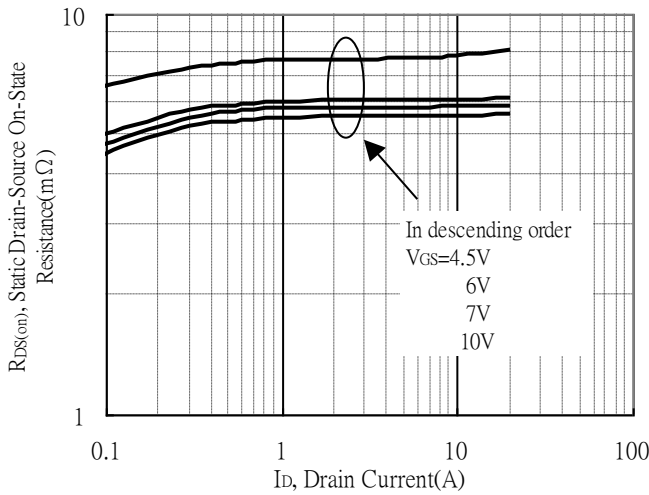
Typical Output Characteristics



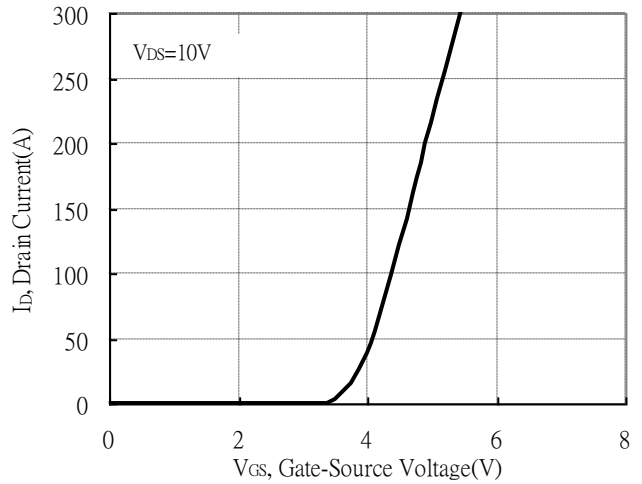
Brekdown Voltage vs Ambient Temperature



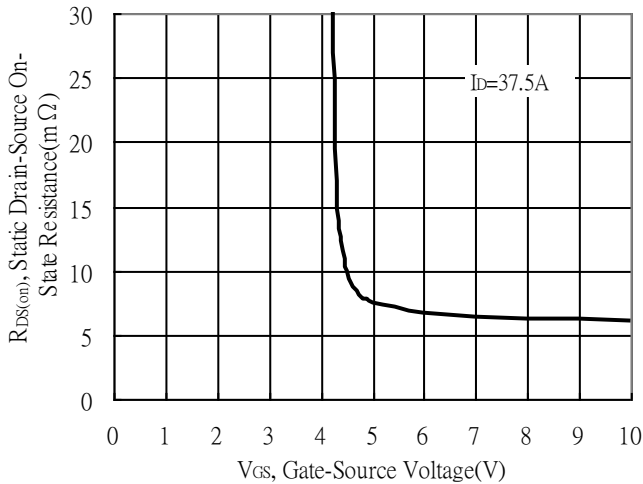
Static Drain-Source On-State resistance vs Drain Current



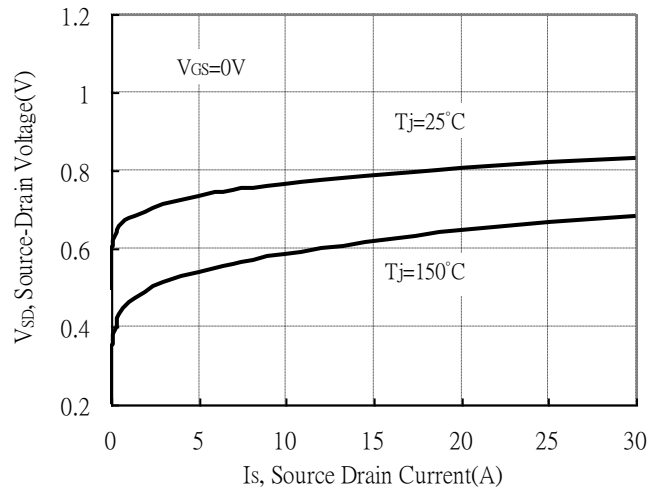
Typical Transfer Characteristics



Static Drain-Source On-State Resistance vs Gate-Source Voltage

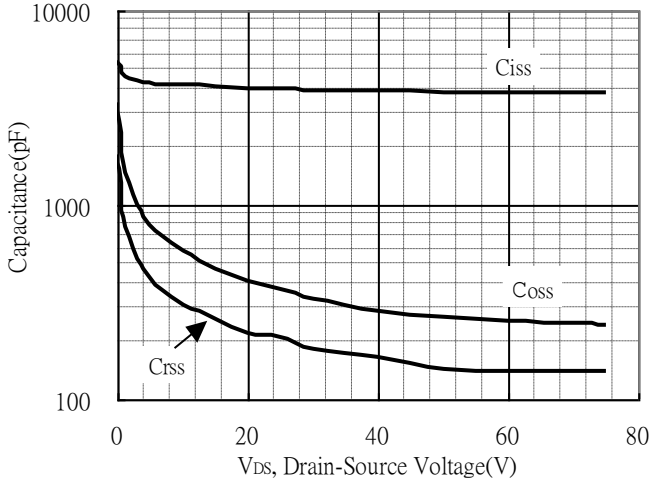


Source Drain Current vs Source-Drain Voltage

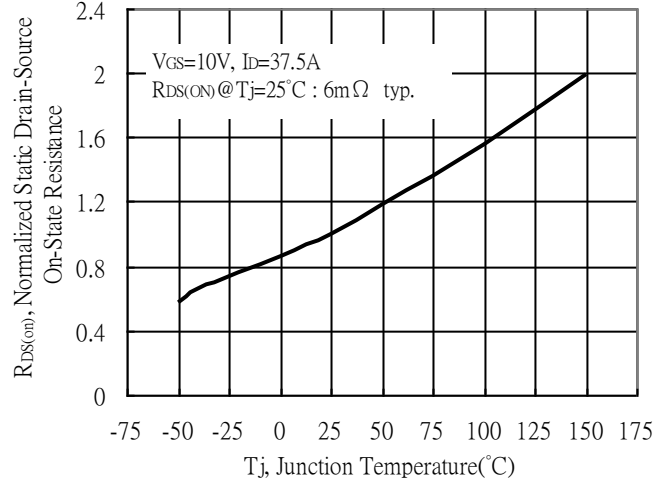


Typical Characteristics(Cont.)

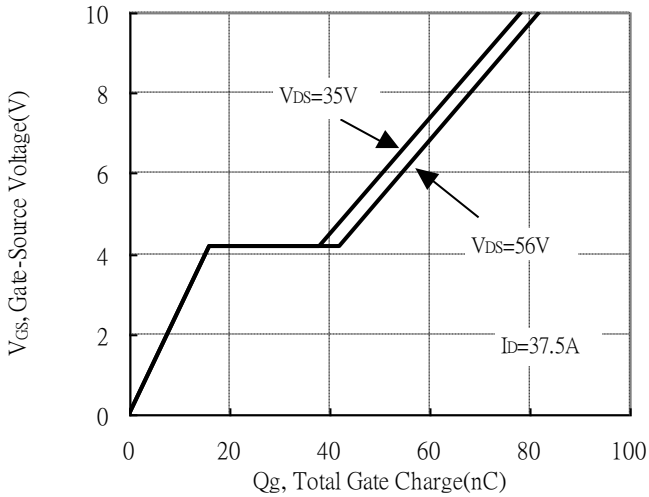
Capacitance vs Drain-to-Source Voltage



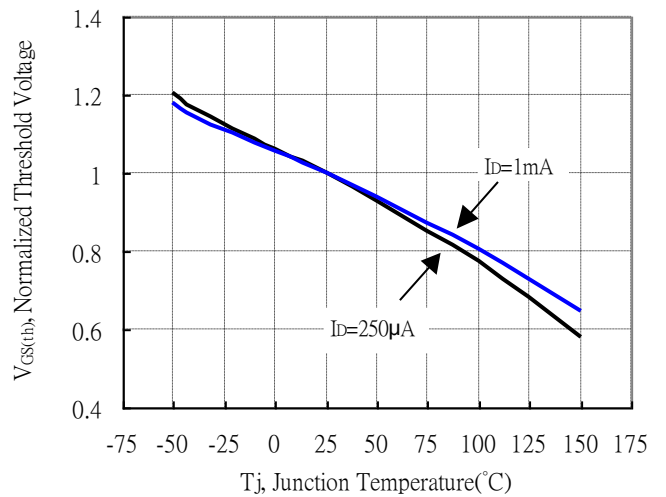
Drain-Source On-State Resistance vs Junction Temperature



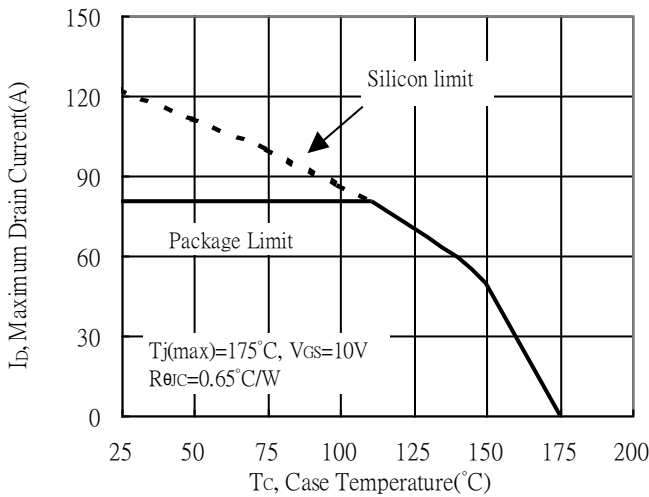
Gate Charge Characteristics



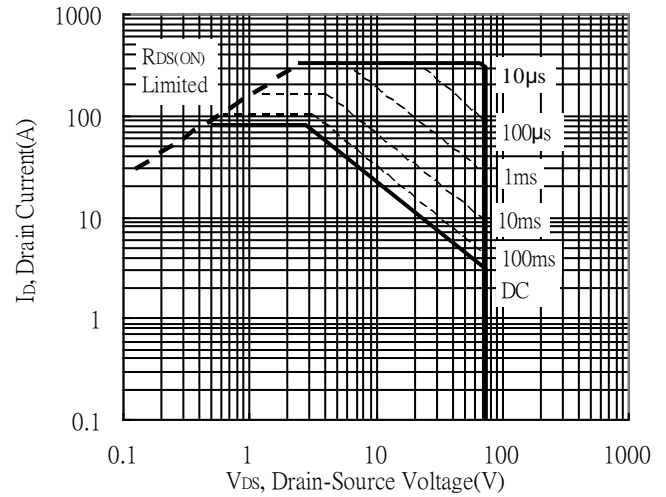
Threshold Voltage vs Junction Temperature



Maximum Drain Current vs Case Temperature

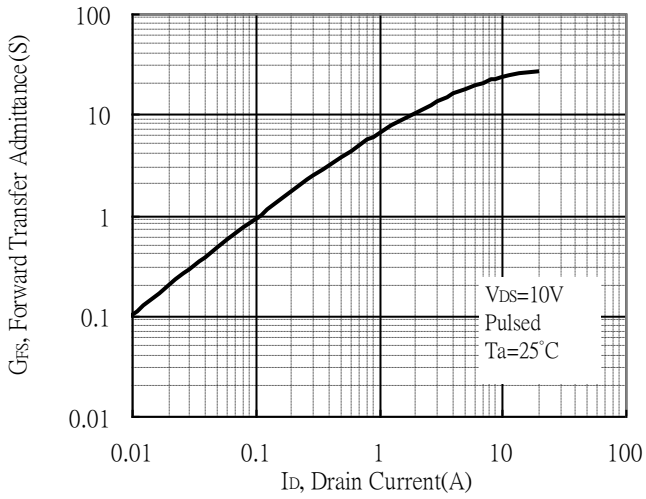


Maximum Safe Operating Area

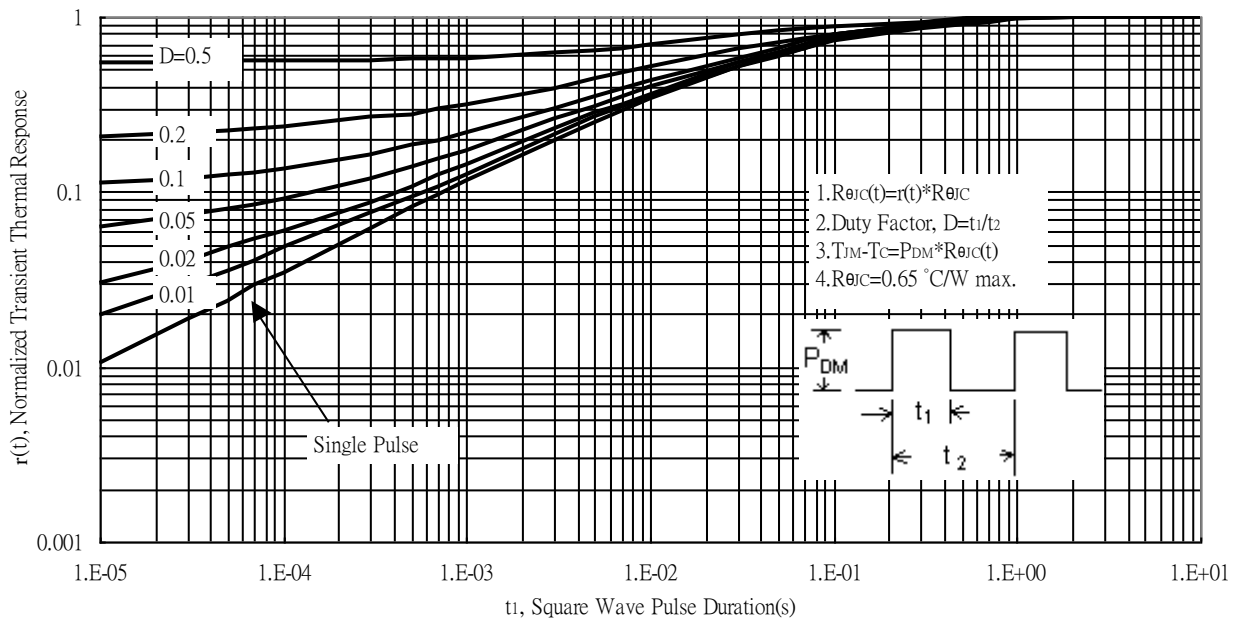


Typical Characteristics(Cont.)

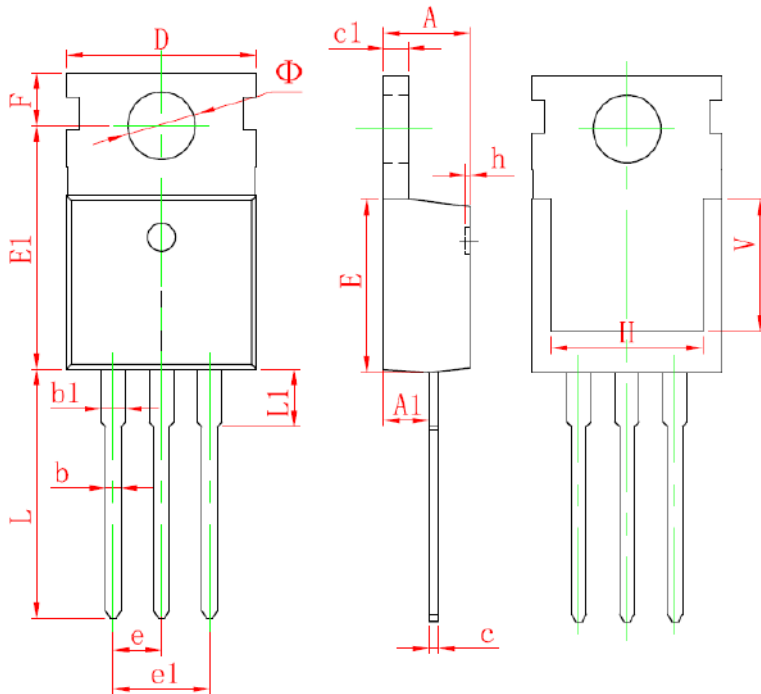
Forward Transfer Admittance vs Drain Current



Transient Thermal Response Curves

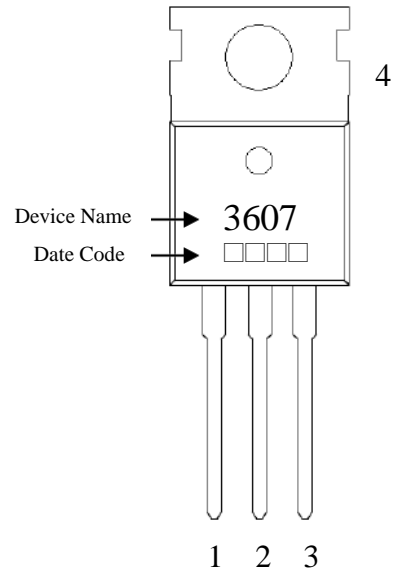


TO-220 Dimension



3-Lead TO-220 Plastic Package

Marking:



Style: Pin 1.Gate 2.Drain 3.Source
 4.Drain

*: Typical

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181	e	2.540*		0.100*	
A1	2.250	2.550	0.089	0.100	e1	4.980	5.180	0.196	0.204
b	0.710	0.910	0.028	0.036	F	2.650	2.950	0.104	0.116
b1	1.170	1.370	0.046	0.054	H	7.900	8.100	0.311	0.319
c	0.330	0.650	0.013	0.026	h	0.000	0.300	0.000	0.012
c1	1.200	1.400	0.047	0.055	L	12.900	13.400	0.508	0.528
D	9.910	10.250	0.390	0.404	L1	2.850	3.250	0.112	0.128
E	8.950	9.750	0.352	0.384	V	7.500	REF	0.295	REF
E1	12.650	12.950	0.498	0.510	Φ	3.400	3.800	0.134	0.150